

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently amended) A method to fix metal fine particles on surface of a substrate by desired fine structure corresponding to irradiation of ~~low lower~~ power and/or ~~low lower~~ density electromagnetic wave comprising;  
~~releasing a part of (a) adding fine particles stabilized by a dispersion stabilizer locating on the surface of metal fine particles by irradiating which can be released by irradiation of~~  
~~high energy electromagnetic wave and/or high energy density electromagnetic wave to a colloidal dispersion of metal fine particles prepared from a solution containing a compound which does not have bonding ability to the dispersing agent and/or metal fine particles with the dispersing agent and/or compound by substituting a part of the dispersing stabilizer, wherein, said dispersing agent is which can be released by irradiation of lower energy electromagnetic wave and/or lower energy density electromagnetic wave from the surface of and/or a compound which does not have bonding ability to the metal fine particles stabilized by to prepare a colloidal dispersion of metal particles which are part of the dispersion stabilizer, which can be released by irradiation of the high energy electromagnetic wave and/or high energy density electromagnetic wave, and being substituted with the dispersing agent and/or compound,~~

~~a process to irradiate~~ (b) irradiating said high energy electromagnetic wave and/or high energy density electromagnetic wave which generate to said prepared colloidal dispersion to release a part of the dispersion stabilizer locating on the surface of metal fine particles which are and generate a dispersion of metal fine particles which is activated so as to cause flocculation of 2-100 times larger to the original particle size to and to improve photo sensitivity of the metal fine particles stabilized by said dispersion stabilizer, and (c) irradiating lower energy electromagnetic wave and/or lower energy density electromagnetic wave to said metal fine particles dispersion whose photo sensitivity is improved by activation.

2. (Original) The method to fix metal fine particles on surface of the substrate by desired fine structure of claim 1, wherein the compound which does not have bonding ability to a dispersing agent released from the surface of the metal fine particles by irradiation of electromagnetic wave of lower energy than a dispersion stabilizer of metal fine particles and/or metal fine particles is a compound whose solvent affinity part is small and/or a compound which causes the release by absorbing said electromagnetic wave.

3. (Original) The method to fix metal fine particles on surface of the substrate by desired fine structure of claim 1,

wherein the dispersion stabilizer is a compound possessing thiol group, amino group, silyl group or cyano group which has high affinity with metal fine particles.

4. (Original) The method to fix metal fine particles on surface of the substrate by desired fine structure of claim 1, wherein the dispersion stabilizer is a compound possessing thiol group, amino group, silyl group or cyano group which has high affinity with metal fine particles, and the compound which does not have bonding ability to a dispersing agent released from the surface of the metal fine particles by irradiation of electromagnetic wave of lower energy than a dispersion stabilizer of metal fine particles and/or metal fine particles is a compound whose solvent affinity part is small and/or a compound which causes the release by absorbing said electromagnetic wave.

5. (Original) The method to fix metal fine particles on surface of the substrate by desired fine structure of claim 3, combining same kinds of electromagnetic waves having different energy intensity and/or different energy density and carrying out at least two steps of irradiation process of electromagnetic wave comprising, at least one step of irradiation process by high energy intensity electromagnetic wave and/or high energy density electromagnetic wave and at least one step of irradiation process by low energy intensity electromagnetic wave and/or low energy

density electromagnetic wave.

6. (Original) The method to fix metal fine particles on surface of the substrate by desired fine structure of claim 4, combining same kinds of electromagnetic waves having different energy intensity and/or different energy density and carrying out at least two steps of irradiation process of electromagnetic wave comprising, at least one step of irradiation process by high energy intensity electromagnetic wave and/or high energy density electromagnetic wave and at least one step of irradiation process by low energy intensity electromagnetic wave and/or low energy density electromagnetic wave.

7. (Original) The method to fix metal fine particles on surface of the substrate by desired fine structure of claim 6, wherein the particle size of the metal fine particles stabilized by a dispersion stabilizer is from 1nm to 100nm.

8. (Original) The method to fix metal fine particles on surface of the substrate by desired fine structure of claim 1, wherein the particle size of the metal fine particles stabilized by a dispersion stabilizer is from 1nm to 100nm.

9. (Original) The method to fix metal fine particles on surface of the substrate by desired fine structure of claim 3, wherein the particle size of the metal fine particles stabilized

by a dispersion stabilizer is from 1nm to 100nm.

10. (Original) The method to fix metal fine particles on surface of the substrate by desired fine structure of claim 4, wherein the particle size of the metal fine particles stabilized by a dispersion stabilizer is from 1nm to 100nm.

11. (Original) The method to fix metal fine particles on surface of the substrate by desired fine structure of claim 1, wherein the dispersing solvent is at least one selected from the group consisting of alicyclic hydrocarbon and aromatic hydrocarbon.

12. (Original) The method to fix metal fine particles on surface of the substrate by desired fine structure of claim 3, wherein the dispersing solvent is at least one selected from the group consisting of alicyclic hydrocarbon and aromatic hydrocarbon.

13. (Original) The method to fix metal fine particles on surface of the substrate by desired fine structure of claim 4, wherein the dispersing solvent is at least one selected from the group consisting of alicyclic hydrocarbon and aromatic hydrocarbon.

14. (Original) The method to fix metal fine particles on surface of the substrate by desired fine structure of claim 5, wherein the dispersing solvent is at least one selected from the group consisting of alicyclic hydrocarbon and aromatic hydrocarbon.

15. (Original) The method to fix metal fine particles on surface of the substrate by desired fine structure of claim 6, wherein the dispersing solvent is at least one selected from the group consisting of alicyclic hydrocarbon and aromatic hydrocarbon.

16. (Original) The method to fix metal fine particles on surface of the substrate by desired fine structure of claim 7, wherein the dispersing solvent is at least one selected from the group consisting of alicyclic hydrocarbon and aromatic hydrocarbon.